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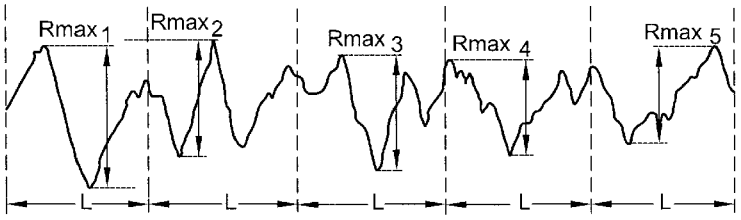


FIG. 1

(57) Abstract: The invention provides a polishing composition comprising silica, an aminophosphonic acid, a polysaccharide, a tetraalkylammonium salt, a bicarbonate salt, a compound comprising an azole ring, and water, wherein the polishing composition has a pH of 7 to 11. The invention further provides a method of polishing a substrate with the polishing composition.

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